



ONS00149

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: : Date: 2/3/2004

CELAYA, PHILLIP et al. : Group: 2827

APPLN. NO. 09/817330 : Examiner: Thiem D. Phan

FILED: 3/26/2001 :

FOR: METHOD OF MAKING AN
INTEGRATED CIRCUIT PACKAGE

I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS BEING DEPOSITED WITH
THE UNITED STATES POSTAL SERVICE AS FIRST CLASS MAIL IN AN ENVELOPE
ADDRESSED TO: COMMISSIONER OF PATENTS AND TRADEMARKS, P.O. Box 1450,
Alexandria, VA 22313-1450,
ON: 2/3/04

Date of Deposit

SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC

Name of Assignee

By: Lydia McNamara 2/3/04

Lydia McNamara

DATE

SUBMITTAL OF FORMAL DRAWINGS

Honorable Commissioner of Patents and Trademarks,
P.O. Box 1450
Alexandria, VA 22313-1450

Attn: Official Draftsman

SIR:

RECEIVED

FEB 17 2004

TECHNOLOGY CENTER

In accordance with the requirement in PTO-948, we
are hereby submitting three (3) sheets of formal drawings
for the above-identified patent application.

The Commissioner is hereby authorized to charge any
fees to Deposit Account 501086.

Respectfully submitted,

Phillip Celaya et al.

Attn: Lydia McNamara
ON Semiconductor
Law Dept./MD A700
P.O. Box 62890
Phoenix, AZ 85082-2890

Kevin B. Jackson
Kevin B. Jackson
Attorney For Applicant(s)
Reg. No. 38,502
Tel. (602) 244-4885
Fax: (602) 244-3169